

DATA SHEET

TDA7088T FM receiver circuit for battery supply

Product specification
Supersedes data of January 1991
File under Integrated Circuits, IC01

1996 May 14

FM receiver circuit for battery supply

TDA7088T

FEATURES

- Equipped with all stages of a mono receiver from antenna to audio output
- Mute circuit
- Search tuning with a single varicap diode
- Mechanical tuning with integrating AFC
- AM application supported
- Power supply polarity protection
- Power supply voltage down to 1.8 V.

APPLICATIONS

- Mechanical tuning; this is possible with or without integrating AFC circuit
- Electrical tuning; this is realized by one directional (band-up) search tuning facility, including RESET to the lower-band limit.

GENERAL DESCRIPTION

The TDA7088T is a bipolar integrated circuit for use in mono portable and pocket radios. It is used when a minimum of peripheral components (of small dimensions and low costs) is important. The circuit contains a frequency-locked-loop (FLL) system with an Intermediate Frequency (IF) of about 70 kHz. Selectivity is achieved by active RC-filters. De-tuning related to the IF and too weak input signals is suppressed by the mute circuit.

QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V_P	supply voltage		1.8	3	5	V
I_P	supply current		4.2	5.2	6.6	mA
f_{iRF}	radio input frequency		0.5	–	110	MHz
$V_{i(rms)}$	RF sensitivity input voltage (RMS value)	$V_{oAF} = -3$ dB; $V_{oAF} = 0$ dB at $V_i = 1$ mV; mute off	–	3	6	μ V
	signal handling	$\Delta f = \pm 75$ kHz; THD < 10%	100	200	–	mV
$V_{o(rms)}$	audio output signal (RMS value)	$R_L = 22$ k Ω	60	85	120	mV
T_{amb}	operating ambient temperature		-10	–	+70	$^{\circ}$ C

ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
TDA7088T	SO16	plastic small outline package; 16 leads; body width 3.9 mm	SOT109-1

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BLOCK DIAGRAM AND APPLICATION CIRCUIT

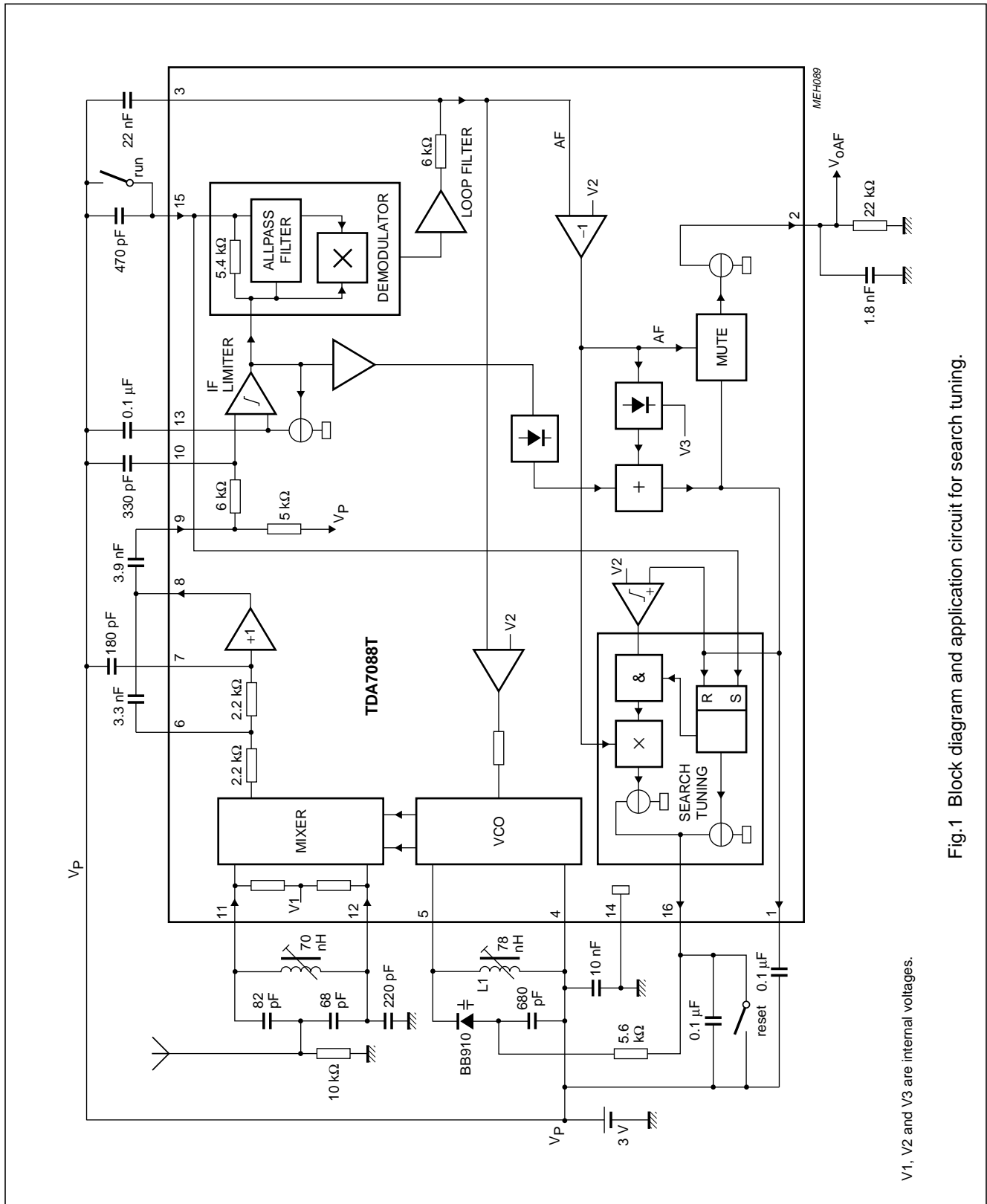


Fig.1 Block diagram and application circuit for search tuning.

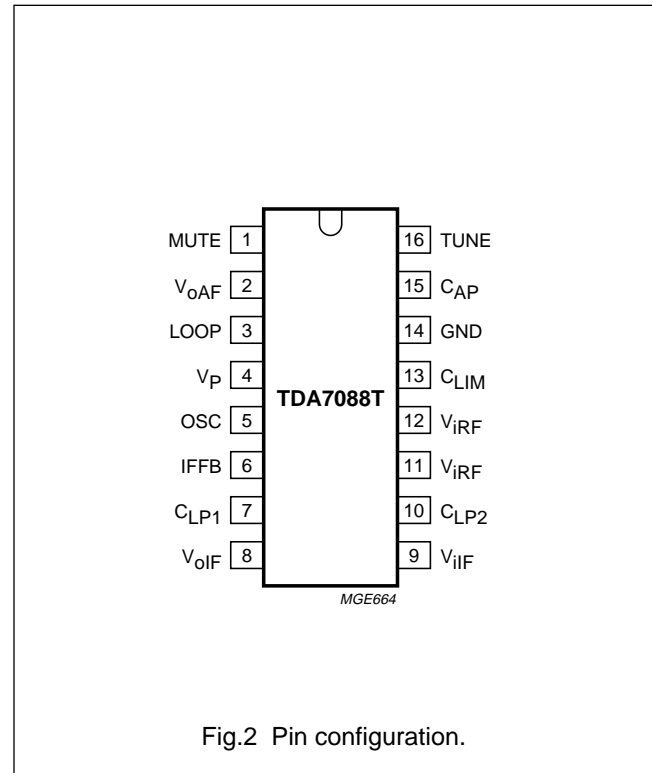
V1, V2 and V3 are internal voltages.

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PINNING

SYMBOL	PIN	DESCRIPTION
MUTE	1	mute output
V _{oAF}	2	audio frequency output signal
LOOP	3	AF loop filter
V _P	4	+3 V supply voltage
OSC	5	oscillator resonant circuit
IFFB	6	IF feedback
C _{LP1}	7	low-pass capacitor of 1 dB amplifier
V _{oIF}	8	IF output to external coupling capacitor (high-pass)
V _{iIF}	9	IF input to limiter amplifier
C _{LP2}	10	low-pass capacitor of IF limiter amplifier
V _{iRF}	11	radio frequency input
V _{iRF}	12	radio frequency input
C _{LIM}	13	limiter offset voltage capacitor
GND	14	ground (0 V)
C _{AP}	15	all-pass filter capacitor/input for search tuning
TUNE	16	electrical tuning/AFC output



LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	MIN.	MAX.	UNIT
V _P	supply voltage	0	5	V
T _{stg}	storage temperature	-55	+150	°C
T _{amb}	operating ambient temperature	-10	+70	°C
V _{es}	electrostatic handling; note 1	-	-	-

Note

1. There is no special ESD protection circuit built-in; ESD data on request.

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DC CHARACTERISTICS

$V_P = 3\text{ V}$; $T_{\text{amb}} = 25\text{ °C}$; unless otherwise specified.

SYMBOL	PARAMETER	MIN.	TYP.	MAX.	UNIT
V_P	supply voltage (pin 4)	1.8	3	5	V
I_P	supply current (pin 4)	4.2	5.2	6.6	mA
V_1	DC voltage on pin 1	2.50	2.55	2.60	V
V_3	DC voltage on pin 3	2.64	2.69	2.74	V
$V_{6,7}$	DC voltage on pins 6 and 7	2.38	2.44	2.50	V
V_8	DC voltage on pin 8	1.60	1.67	1.74	V
$V_{9,10,13}$	DC voltage on pins 9, 10 and 13	2.42	2.47	2.52	V
$V_{11,12}$	DC voltage on pins 11 and 12	0.91	0.94	0.98	V
V_{15}	DC voltage on pin 15	2.06	2.12	2.18	V
I_2	AF output current on pin 2	45	60	80	μA
I_5	oscillator current on pin 5	275	375	500	μA

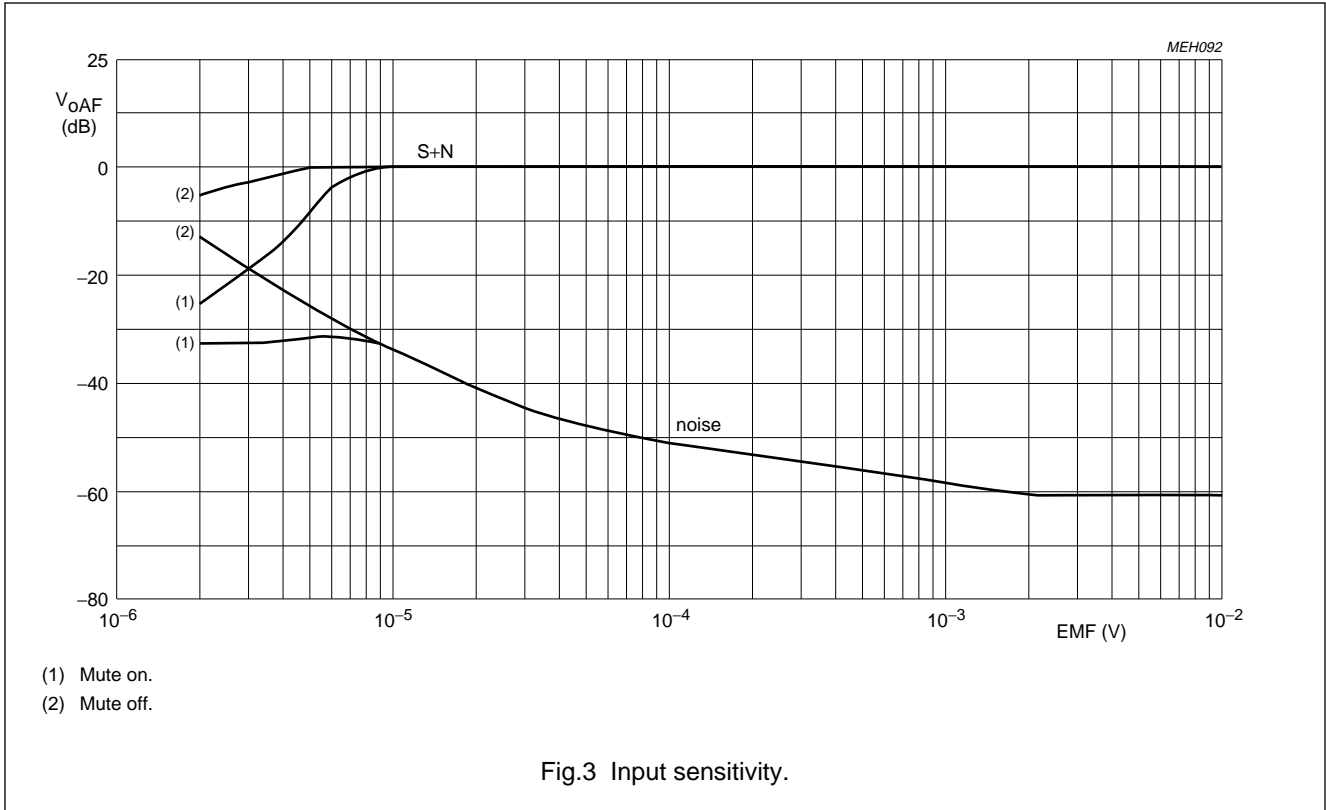
AC CHARACTERISTICS

$V_P = 3\text{ V}$; $T_{\text{amb}} = 25\text{ °C}$; $f_{\text{IRF}} = 96\text{ MHz}$ modulated with $f_{\text{mod}} = 1\text{ kHz}$ and $\pm 22.5\text{ kHz}$ deviation; $V_i = 400\text{ }\mu\text{V}$ (measured as EMF; $R_S = 75\text{ }\Omega$) and measurements taken in Fig.4; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$V_{i(\text{rms})}$	RF sensitivity input voltage (RMS value)	$V_{\text{OAF}} = -3\text{ dB}$; $V_{\text{OAF}} = 0\text{ dB}$ at $V_i = 1\text{ mV}$; see Fig.3				
		mute off	–	3	6	μV
		mute on	3	6	12	μV
		$\frac{S+N}{N} = 26\text{ dB}$	–	5	10	μV
	signal handling	$\Delta f = \pm 75\text{ kHz}$; THD < 10%	100	200	–	mV
$\frac{S+N}{N}$	signal plus noise-to-noise ratio	see Fig.3	52	56	–	dB
THD	total harmonic distortion	$\Delta f = \pm 22.5\text{ kHz}$	–	1	1.4	%
		$\Delta f = \pm 75\text{ kHz}$	–	2.4	3.3	%
α_{AM}	AM suppression	FM: 1 kHz; $\pm 75\text{ kHz}$; AM: 1 kHz; $m = 0.8$	47	52	–	dB
RR_{1000}	ripple rejection	100 mV RMS ripple on V_P ; $f = 1\text{ kHz}$	7	10	–	dB
$V_{o(\text{rms})}$	audio output signal (RMS value)	$R_L = 22\text{ k}\Omega$	60	85	120	mV
Search tuning (with BB910 and $C_{16} = 0.1\text{ }\mu\text{F}$) see Fig.1						
V_{16}	minimum output voltage on pin 16	limiting point	–	$V_P - 1.85$	–	V
$\Delta V/\Delta t$	tuning steepness	voltage at pin 16	95	210	420	mV/s
$\Delta f_{\text{osc}}/\Delta t$	oscillator steepness		1.25	2.83	5.6	MHz/s
$\Delta I_{\text{AFC}}/\Delta V_3$	AFC steepness	voltage at pin 3	4.75	9.5	19	μS

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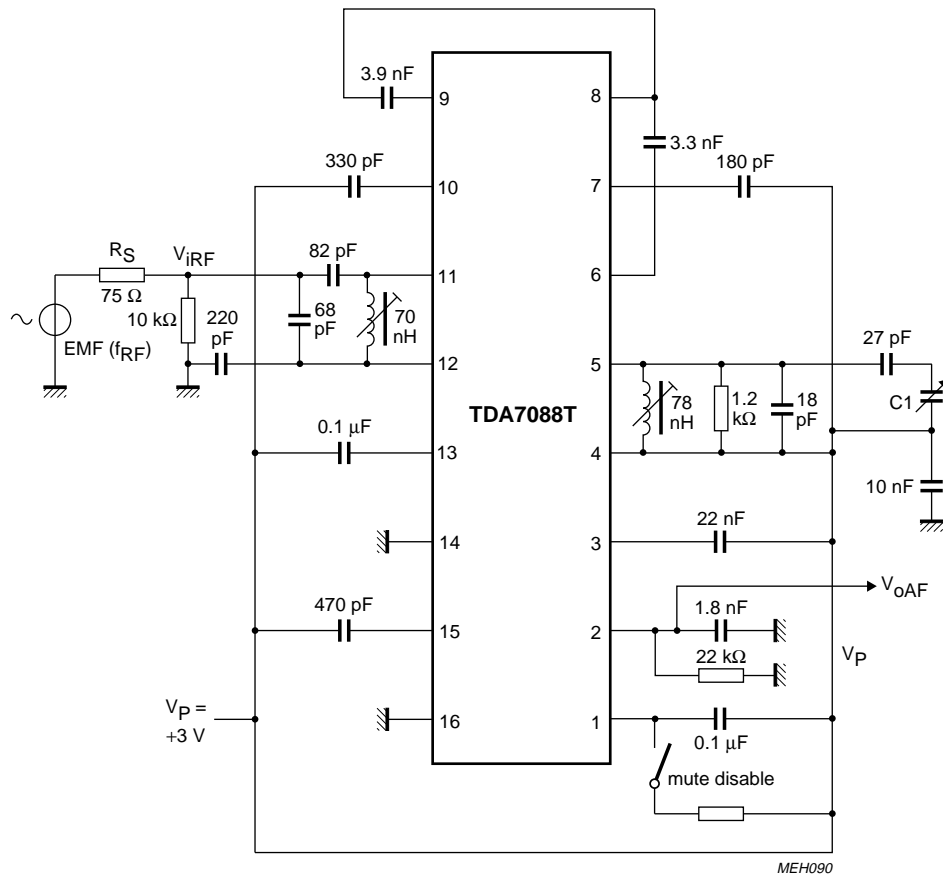
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TEST AND APPLICATION INFORMATION

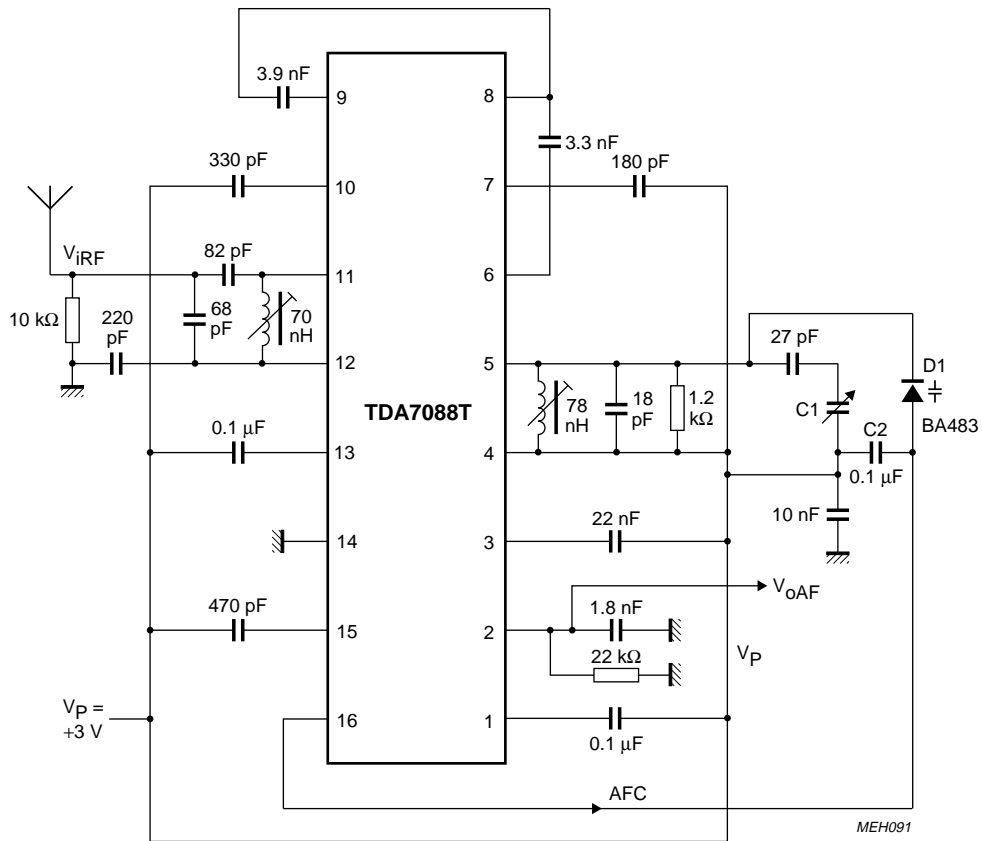


C1 = Toko 2A-15BT-R01.

Fig.4 Test circuit and application for mechanical tuning.

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C1 = Toko 2A-15BT-R01.

Fig.5 Application circuit with AFC for mechanical tuning.

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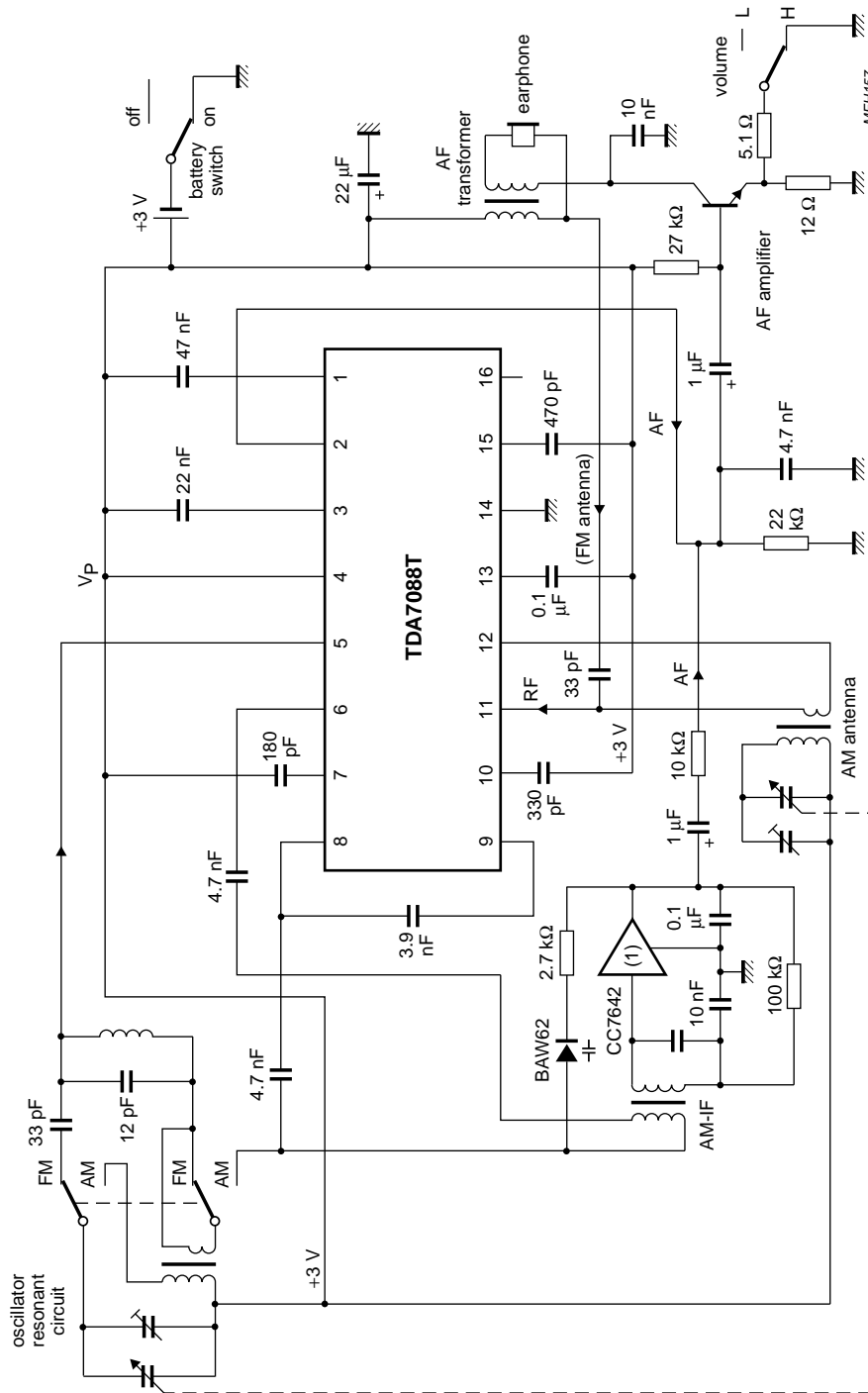


Fig.6 AM application circuit.

(1) CC7642: AM-IF amplifier/demodulator type number WU-xi 742 Fty.

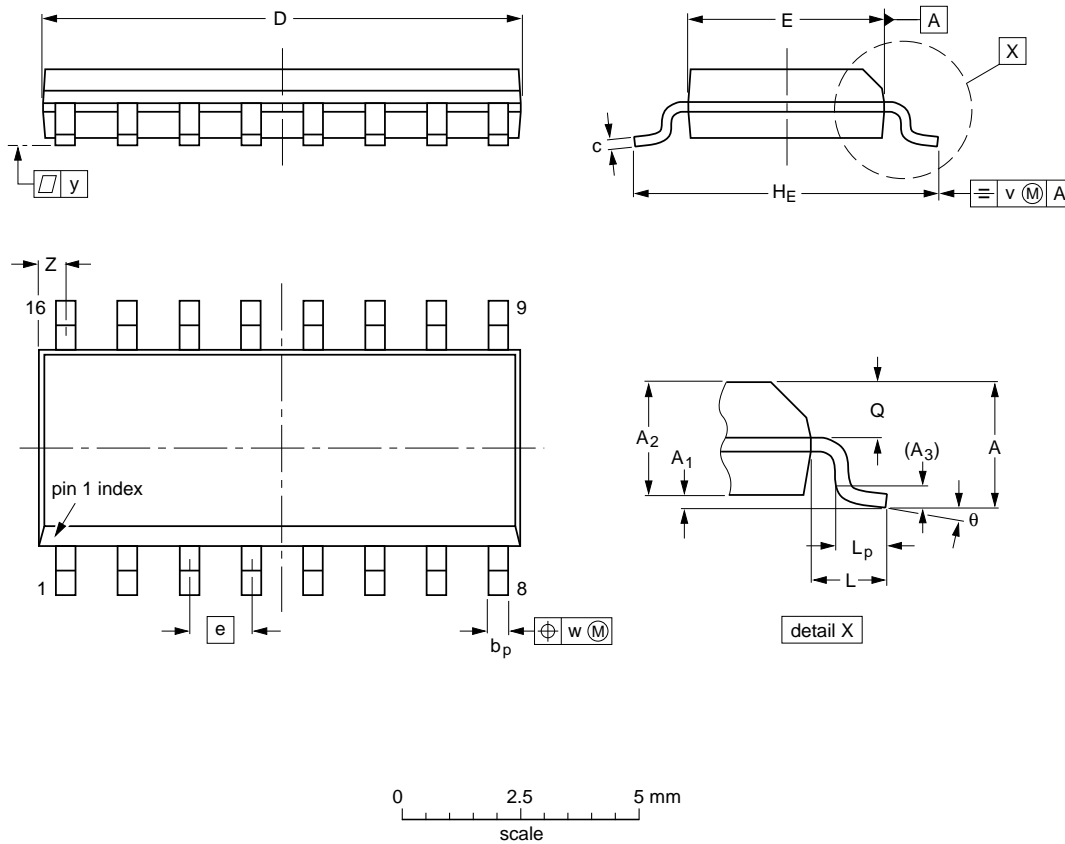
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PACKAGE OUTLINE

SOT16: plastic small outline package; 16 leads; body width 3.9 mm

SOT109-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _E	L	L _p	Q	v	w	y	Z ⁽¹⁾	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	10.0 9.8	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8° 0°
inches	0.069	0.0098 0.0039	0.057 0.049	0.01	0.019 0.014	0.0098 0.0075	0.39 0.38	0.16 0.15	0.050	0.24 0.23	0.041	0.039 0.016	0.028 0.020	0.01	0.01	0.004	0.028 0.012	

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT109-1	076E07S	MS-012AC				91-08-13 95-01-23

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SOLDERING

Introduction

There is no soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and surface mounted components are mixed on one printed-circuit board. However, wave soldering is not always suitable for surface mounted ICs, or for printed-circuits with high population densities. In these situations reflow soldering is often used.

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our *"IC Package Databook"* (order code 9398 652 90011).

Reflow soldering

Reflow soldering techniques are suitable for all SO packages.

Reflow soldering requires solder paste (a suspension of fine solder particles, flux and binding agent) to be applied to the printed-circuit board by screen printing, stencilling or pressure-syringe dispensing before package placement.

Several techniques exist for reflowing; for example, thermal conduction by heated belt. Dwell times vary between 50 and 300 seconds depending on heating method. Typical reflow temperatures range from 215 to 250 °C.

Preheating is necessary to dry the paste and evaporate the binding agent. Preheating duration: 45 minutes at 45 °C.

Wave soldering

Wave soldering techniques can be used for all SO packages if the following conditions are observed:

- A double-wave (a turbulent wave with high upward pressure followed by a smooth laminar wave) soldering technique should be used.
- The longitudinal axis of the package footprint must be parallel to the solder flow.
- The package footprint must incorporate solder thieves at the downstream end.

During placement and before soldering, the package must be fixed with a droplet of adhesive. The adhesive can be applied by screen printing, pin transfer or syringe dispensing. The package can be soldered after the adhesive is cured.

Maximum permissible solder temperature is 260 °C, and maximum duration of package immersion in solder is 10 seconds, if cooled to less than 150 °C within 6 seconds. Typical dwell time is 4 seconds at 250 °C.

A mildly-activated flux will eliminate the need for removal of corrosive residues in most applications.

Repairing soldered joints

Fix the component by first soldering two diagonally-opposite end leads. Use only a low voltage soldering iron (less than 24 V) applied to the flat part of the lead. Contact time must be limited to 10 seconds at up to 300 °C. When using a dedicated tool, all other leads can be soldered in one operation within 2 to 5 seconds between 270 and 320 °C.

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DEFINITIONS

Data sheet status	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
Limiting values	
Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.	
Application information	
Where application information is given, it is advisory and does not form part of the specification.	

LIFE SUPPORT APPLICATIONS

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NOTES

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